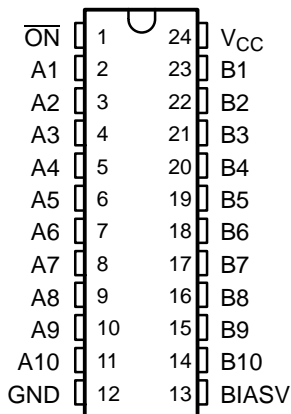


## FEATURES

- High-Bandwidth Data Path (Up To 500 MHz <sup>(1)</sup>)
  - 5-V Tolerant I/Os With Device Powered Up or Powered Down
  - Low and Flat ON-State Resistance ( $r_{on}$ ) Characteristics Over Operating Range ( $r_{on} = 4.5 \Omega$  Typ)
  - Rail-to-Rail Switching on Data I/O Ports
    - 0- to 5-V Switching With 3.3-V  $V_{CC}$
    - 0- to 3.3-V Switching With 2.5-V  $V_{CC}$
  - B-Port Outputs Are Precharged by Bias Voltage (BIASV) to Minimize Signal Distortion During Live Insertion and Hot Plugging
  - Supports PCI Hot Plug
  - Bidirectional Data Flow With Near-Zero Propagation Delay
  - Low Input/Output Capacitance Minimizes Loading and Signal Distortion ( $C_{io(OFF)} = 3.5$  pF Typ)
- (1) For additional information regarding the performance characteristics of the CB3Q family, refer to the TI application report, *CBT-C, CB3T, and CB3Q Signal-Switch Families*, literature number SCDA008.
- Fast Switching Frequency ( $f_{ON} = 20$  MHz Max)
  - Data and Control Inputs Provide Undershoot Clamp Diodes
  - Low Power Consumption ( $I_{CC} = 0.75$  mA Typ)
  - $V_{CC}$  Operating Range From 2.3 V to 3.6 V
  - Data I/Os Support 0- to 5-V Signaling Levels (0.8 V, 1.2 V, 1.5 V, 1.8 V, 2.5 V, 3.3 V, 5 V)
  - Control Inputs Can Be Driven by TTL or 5-V/3.3-V CMOS Outputs
  - $I_{off}$  Supports Partial-Power-Down Mode Operation
  - Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
  - ESD Performance Tested Per JESD 22
    - 2000-V Human-Body Model (A114-B, Class II)
    - 1000-V Charged-Device Model (C101)
  - Supports Both Digital and Analog Applications: PCI Interface, Differential Signal Interface, Memory Interleaving, Bus Isolation, Low-Distortion Signal Gating

DBQ, DGV, OR PW PACKAGE  
(TOP VIEW)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

**SN74CB3Q6800**  
**10-BIT FET BUS SWITCH WITH PRECHARGED OUTPUTS**  
**2.5-V/3.3-V LOW-VOLTAGE HIGH-BANDWIDTH BUS SWITCH**

SCDS142A–OCTOBER 2003–REVISED MARCH 2005

## DESCRIPTION/ORDERING INFORMATION

The SN74CB3Q6800 is a high-bandwidth FET bus switch utilizing a charge pump to elevate the gate voltage of the pass transistor, providing a low and flat ON-state resistance ( $r_{on}$ ). The low and flat ON-state resistance allows for minimal propagation delay and supports rail-to-rail switching on the data input/output (I/O) ports. The device also features low data I/O capacitance to minimize capacitive loading and signal distortion on the data bus. Specifically designed to support high-bandwidth applications, the SN74CB3Q6800 provides an optimized interface solution ideally suited for broadband communications, networking, and data-intensive computing systems.

The SN74CB3Q6800 is a 10-bit bus switch with a single output-enable ( $\overline{ON}$ ) input. When  $\overline{ON}$  is low, the 10-bit bus switch is ON and the A port is connected to the B port, allowing bidirectional data flow between ports. When  $\overline{ON}$  is high, the 10-bit bus switch is OFF and a high-impedance state exists between the A and B ports. The B port is precharged to bias voltage (BIASV) through the equivalent of a 10-k $\Omega$  resistor when  $\overline{ON}$  is high, or if the device is powered down ( $V_{CC} = 0$  V).

During insertion (or removal) of a card into (or from) an active bus, the card's output voltage may be close to GND. When the connector pins make contact, the card's parasitic capacitance tries to force the bus signal to GND, creating a possible glitch on the active bus. This glitching effect can be reduced by using a bus switch with precharged bias voltage (BIASV) of the bus switch equal to the input threshold voltage level of the receivers on the active bus. This method ensures that any glitch produced by insertion (or removal) of the card does not cross the input threshold region of the receivers on the active bus, minimizing the effects of live-insertion noise.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry prevents damaging current backflow through the device when it is powered down. The device has isolation during power off.

To ensure the high-impedance state during power up or power down,  $\overline{ON}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

## ORDERING INFORMATION

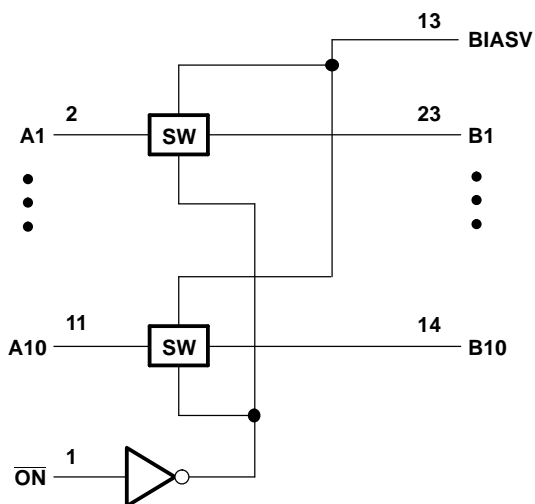
| $T_A$         | PACKAGE <sup>(1)</sup> |               | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|---------------|------------------------|---------------|-----------------------|------------------|
| –40°C to 85°C | SSOP (QSOP) – DBQ      | Tape and reel | SN74CB3Q6800DBQR      | CB3Q6800         |
|               | TSSOP – PW             | Tube          | SN74CB3Q6800PW        | BY800            |
|               |                        | Tape and reel | SN74CB3Q6800PWR       |                  |
|               | TVSOP – DGV            | Tape and reel | SN74CB3Q6800DGVR      | BY800            |

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

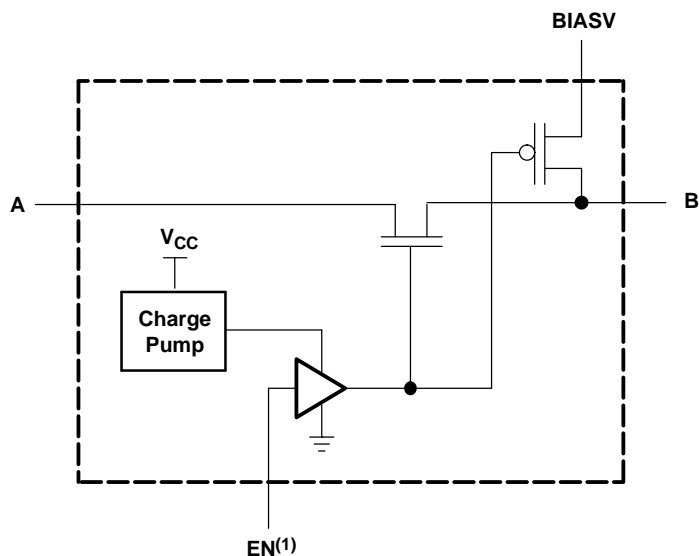
## FUNCTION TABLE

| INPUT<br>$\overline{ON}$ | INPUT/OUTPUT<br>A | FUNCTION                     |
|--------------------------|-------------------|------------------------------|
| L                        | B                 | A port = B port              |
| H                        | Z                 | Disconnect<br>B port = BIASV |

### LOGIC DIAGRAM (POSITIVE LOGIC)



### SIMPLIFIED SCHEMATIC, EACH FET SWITCH (SW)



(1) EN is the internal enable signal applied to the switch.

**SN74CB3Q6800**  
**10-BIT FET BUS SWITCH WITH PRECHARGED OUTPUTS**  
**2.5-V/3.3-V LOW-VOLTAGE HIGH-BANDWIDTH BUS SWITCH**

SCDS142A–OCTOBER 2003–REVISED MARCH 2005

## Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

|               |                                               |               | MIN  | MAX  | UNIT |
|---------------|-----------------------------------------------|---------------|------|------|------|
| $V_{CC}$      | Supply voltage range                          |               | –0.5 | 4.6  | V    |
| BIASV         | BIAS supply voltage range                     |               | –0.5 | 7    | V    |
| $V_{IN}$      | Control input voltage range <sup>(2)(3)</sup> |               | –0.5 | 7    | V    |
| $V_{I/O}$     | Switch I/O voltage range <sup>(2)(3)(4)</sup> |               | –0.5 | 7    | V    |
| $I_{IK}$      | Control input clamp current                   | $V_{IN} < 0$  |      | –50  | mA   |
| $I_{I/OK}$    | I/O port clamp current                        | $V_{I/O} < 0$ |      | –50  | mA   |
| $I_{I/O}$     | ON-state switch current <sup>(5)</sup>        |               |      | ±64  | mA   |
|               | Continuous current through $V_{CC}$ or GND    |               |      | ±100 | mA   |
| $\theta_{JA}$ | Package thermal impedance <sup>(6)</sup>      | DBG package   |      | 61   | °C/W |
|               |                                               | DGV package   |      | 86   |      |
|               |                                               | PW package    |      | 88   |      |
| $T_{stg}$     | Storage temperature range                     |               | –65  | 150  | °C   |

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltages are with respect to ground, unless otherwise specified.
- (3) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (4)  $V_I$  and  $V_O$  are used to denote specific conditions for  $V_{I/O}$ .
- (5)  $I_I$  and  $I_O$  are used to denote specific conditions for  $I_{I/O}$ .
- (6) The package thermal impedance is calculated in accordance with JESD 51-7.

## Recommended Operating Conditions<sup>(1)</sup>

|           |                                  |                                            | MIN | MAX | UNIT |
|-----------|----------------------------------|--------------------------------------------|-----|-----|------|
| $V_{CC}$  | Supply voltage                   |                                            | 2.3 | 3.6 | V    |
| BIASV     | Bias supply voltage              |                                            | 0   | 5   | V    |
| $V_{IH}$  | High-level control input voltage | $V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$ | 1.7 | 5.5 | V    |
|           |                                  | $V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$ | 2   | 5.5 |      |
| $V_{IL}$  | Low-level control input voltage  | $V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$ | 0   | 0.7 | V    |
|           |                                  | $V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$ | 0   | 0.8 |      |
| $V_{I/O}$ | Data input/output voltage        |                                            | 0   | 5.5 | V    |
| $T_A$     | Operating free-air temperature   |                                            | –40 | 85  | °C   |

- (1) All unused control inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004. BIASV is a supply voltage, not a control input.

## Electrical Characteristics<sup>(1)</sup>

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER             |                   | TEST CONDITIONS                                                        |                                                                                                     | MIN | TYP <sup>(2)</sup> | MAX  | UNIT       |
|-----------------------|-------------------|------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------|-----|--------------------|------|------------|
| $V_{IK}$              |                   | $V_{CC} = 3.6\text{ V}$ ,                                              | $I_I = -18\text{ mA}$                                                                               |     |                    | -1.8 | V          |
| $I_{IN}$              | Control inputs    | $V_{CC} = 3.6\text{ V}$ ,                                              | $V_{IN} = 0\text{ to }5.5\text{ V}$                                                                 |     |                    | ±1   | μA         |
| $I_O$                 | B port            | $V_{CC} = 3\text{ V}$ ,                                                | BIASV = 2.4 V,<br>$V_O = 0$ ,<br>Switch OFF,<br>$V_{IN} = V_{CC}\text{ or GND}$                     |     | 0.2                |      | mA         |
| $I_{OZ}^{(3)}$        |                   | $V_{CC} = 3.6\text{ V}$ ,                                              | $V_O = 0\text{ to }5.5\text{ V}$ ,<br>$V_I = 0$ ,<br>Switch OFF,<br>$V_{IN} = V_{CC}\text{ or GND}$ |     |                    | ±1   | μA         |
| $I_{off}$             |                   | $V_{CC} = 0$ ,                                                         | $V_O = 0\text{ to }5.5\text{ V}$ ,<br>$V_I = 0$                                                     |     |                    | 1    | μA         |
| $I_{CC}$              |                   | $V_{CC} = 3.6\text{ V}$ ,                                              | $I_{I/O} = 0$ ,<br>Switch ON or OFF,<br>$V_{IN} = V_{CC}\text{ or GND}$                             |     | 0.75               | 2    | mA         |
| $\Delta I_{CC}^{(4)}$ | Control inputs    | $V_{CC} = 3.6\text{ V}$ ,                                              | One input at 3 V,<br>Other inputs at $V_{CC}\text{ or GND}$                                         |     |                    | 30   | μA         |
| $I_{CCD}^{(5)}$       | Per control input | $V_{CC} = 3.6\text{ V}$ ,<br>Control input switching at 50% duty cycle | A and B ports open,                                                                                 |     | 0.38               | 0.45 | mA/<br>MHz |
| $C_{in}$              | Control inputs    | $V_{CC} = 3.3\text{ V}$ ,                                              | $V_{IN} = 5.5\text{ V}$ , 3.3 V, or 0                                                               |     | 2.5                | 3.5  | pF         |
| $C_{io(OF)}$<br>F)    | A port            | $V_{CC} = 3.3\text{ V}$ ,                                              | Switch OFF,<br>$V_{IN} = V_{CC}\text{ or GND}$ ,<br>$V_{I/O} = 5.5\text{ V}$ , 3.3 V, or 0          |     | 3.5                | 5    | pF         |
| $C_{io(ON)}$          |                   | $V_{CC} = 3.3\text{ V}$ ,                                              | Switch ON,<br>$V_{IN} = V_{CC}\text{ or GND}$ ,<br>$V_{I/O} = 5.5\text{ V}$ , 3.3 V, or 0           |     | 9                  | 11   | pF         |
| $r_{on}^{(6)}$        |                   | $V_{CC} = 2.3\text{ V}$ ,<br>TYP at $V_{CC} = 2.5\text{ V}$            | $V_I = 0$ ,<br>$I_O = 30\text{ mA}$                                                                 |     | 4.5                | 8    | Ω          |
|                       |                   |                                                                        | $V_I = 1.7\text{ V}$ ,<br>$I_O = -15\text{ mA}$                                                     |     | 4.8                | 9    |            |
|                       |                   | $V_{CC} = 3\text{ V}$                                                  | $V_I = 0$ ,<br>$I_O = 30\text{ mA}$                                                                 |     | 4.5                | 6    |            |
|                       |                   |                                                                        | $V_I = 2.4\text{ V}$ ,<br>$I_O = -15\text{ mA}$                                                     |     | 4.6                | 8    |            |

(1)  $V_{IN}$  and  $I_{IN}$  refer to control inputs.  $V_I$ ,  $V_O$ ,  $I_I$ , and  $I_O$  refer to data pins.

(2) All typical values are at  $V_{CC} = 3.3\text{ V}$  (unless otherwise noted),  $T_A = 25^\circ\text{C}$ .

(3) For I/O ports, the parameter  $I_{OZ}$  includes the input leakage current.

(4) This is the increase in supply current for each input that is at the specified TTL voltage level, rather than  $V_{CC}$  or GND.

(5) This parameter specifies the dynamic power-supply current associated with the operating frequency of a single control input (see Figure 2).

(6) Measured by the voltage drop between the A and B terminals at the indicated current through the switch. ON-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

## Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3)

| PARAMETER      | TEST CONDITIONS | FROM<br>(INPUT) | TO<br>(OUTPUT) | $V_{CC} = 2.5\text{ V}$<br>$\pm 0.2\text{ V}$ |       | $V_{CC} = 3.3\text{ V}$<br>$\pm 0.3\text{ V}$ |       | UNIT |
|----------------|-----------------|-----------------|----------------|-----------------------------------------------|-------|-----------------------------------------------|-------|------|
|                |                 |                 |                | MIN                                           | MAX   | MIN                                           | MAX   |      |
| $f_{ON}^{(1)}$ |                 | $\overline{ON}$ | A or B         |                                               | 10    |                                               | 20    | MHz  |
| $t_{pd}^{(2)}$ |                 | A or B          | B or A         |                                               | 0.135 |                                               | 0.225 | ns   |
| $t_{pZH}$      | BIASV = GND     | $\overline{ON}$ | A or B         | 1.5                                           | 8.5   | 1.5                                           | 6.7   | ns   |
| $t_{pZL}$      | BIASV = 3 V     |                 |                | 1.5                                           | 8.5   | 1.5                                           | 6.7   |      |
| $t_{PHZ}$      | BIASV = GND     | $\overline{ON}$ | A or B         | 1                                             | 5     | 1                                             | 5     | ns   |
| $t_{PLZ}$      | BIASV = 3 V     |                 |                | 1                                             | 6.9   | 1                                             | 6.9   |      |

(1) Maximum switching frequency for control input ( $V_O > V_{CC}$ ,  $V_I = 5\text{ V}$ ,  $R_L \geq 1\text{ M}\Omega$ ,  $C_L = 0$ ).

(2) The propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

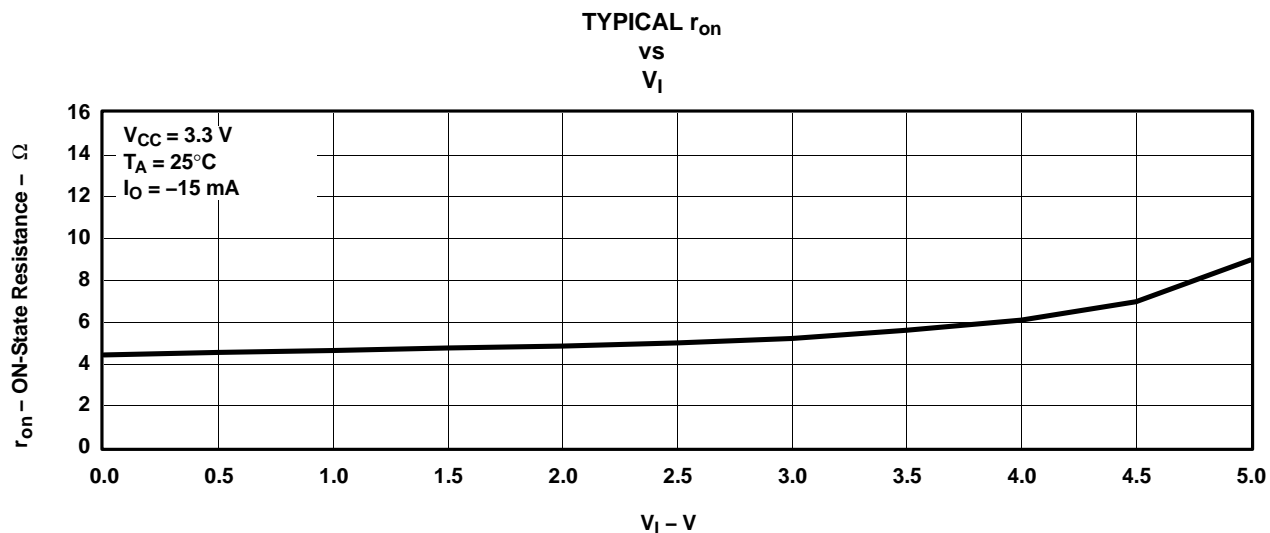


Figure 1. Typical  $r_{on}$  vs  $V_I$

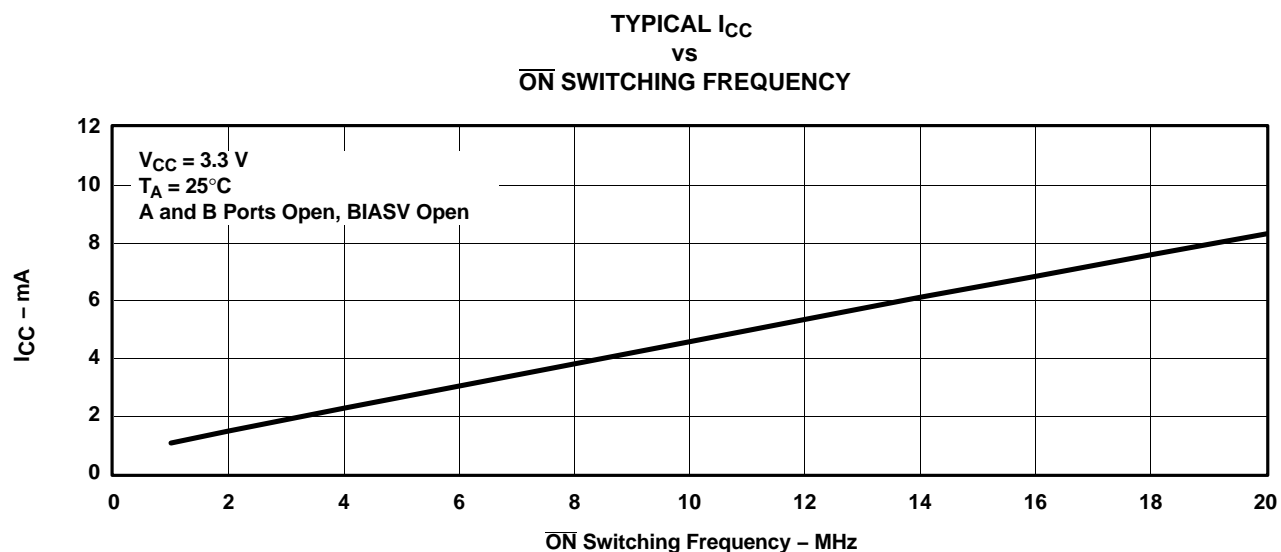
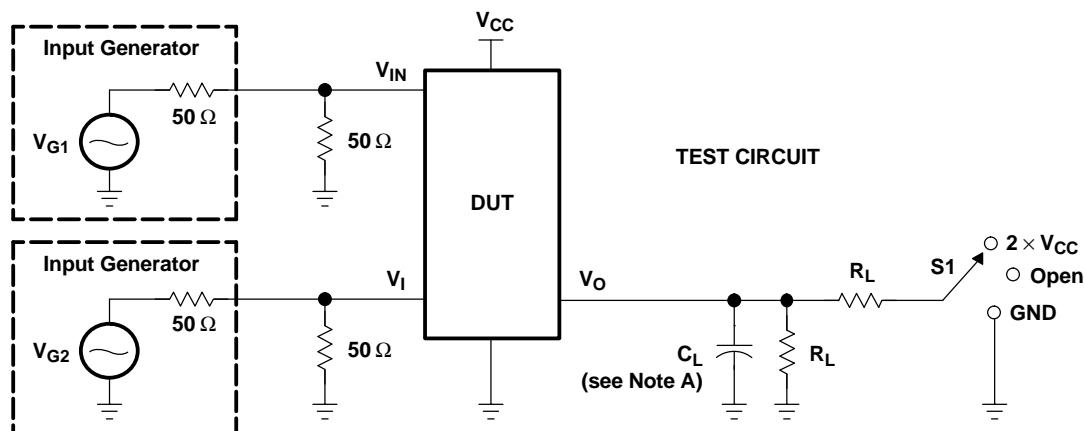
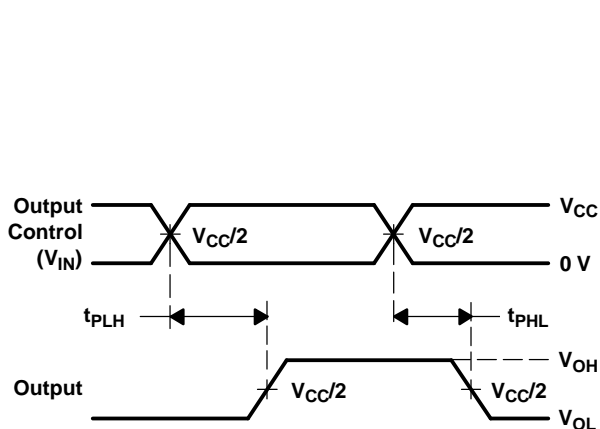


Figure 2. Typical  $I_{CC}$  vs  $\overline{ON}$  Switching Frequency

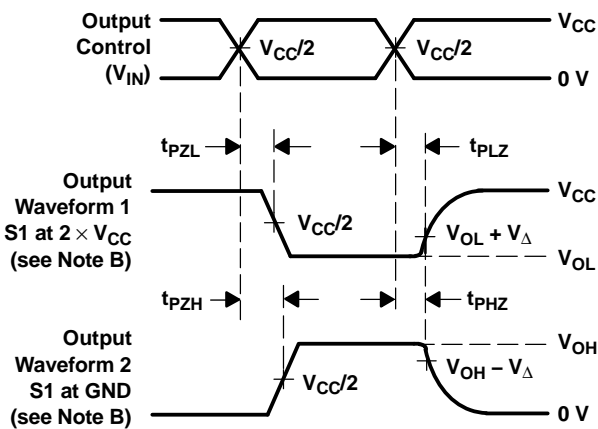
## PARAMETER MEASUREMENT INFORMATION



| TEST                               | V <sub>CC</sub>                | S1                                         | R <sub>L</sub> | V <sub>I</sub>                                   | C <sub>L</sub> | V <sub>Δ</sub>  |
|------------------------------------|--------------------------------|--------------------------------------------|----------------|--------------------------------------------------|----------------|-----------------|
| t <sub>pd(s)</sub>                 | 2.5 V ± 0.2 V<br>3.3 V ± 0.3 V | Open<br>Open                               | 500 Ω<br>500 Ω | V <sub>CC</sub> or GND<br>V <sub>CC</sub> or GND | 30 pF<br>50 pF |                 |
| t <sub>PLZ</sub> /t <sub>PZL</sub> | 2.5 V ± 0.2 V<br>3.3 V ± 0.3 V | 2 × V <sub>CC</sub><br>2 × V <sub>CC</sub> | 500 Ω<br>500 Ω | GND<br>GND                                       | 30 pF<br>50 pF | 0.15 V<br>0.3 V |
| t <sub>PHZ</sub> /t <sub>PZH</sub> | 2.5 V ± 0.2 V<br>3.3 V ± 0.3 V | GND<br>GND                                 | 500 Ω<br>500 Ω | V <sub>CC</sub><br>V <sub>CC</sub>               | 30 pF<br>50 pF | 0.15 V<br>0.3 V |



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES (t<sub>pd(s)</sub>)



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES

- NOTES:
- C<sub>L</sub> includes probe and jig capacitance.
  - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z<sub>O</sub> = 50 Ω, t<sub>r</sub> ≤ 2.5 ns, t<sub>f</sub> ≤ 2.5 ns.
  - The outputs are measured one at a time with one transition per measurement.
  - t<sub>PLZ</sub> and t<sub>PZH</sub> are the same as t<sub>dis</sub>.
  - t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
  - t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd(s)</sub>. The t<sub>pd</sub> propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).
  - All parameters and waveforms are not applicable to all devices.

Figure 3. Test Circuit and Voltage Waveforms

## PACKAGING INFORMATION

| Orderable Device   | Status<br>(1) | Package Type | Package<br>Drawing | Pins | Package<br>Qty | Eco Plan<br>(2)            | Lead/Ball Finish | MSL Peak Temp<br>(3) | Op Temp (°C) | Top-Side Markings<br>(4) | Samples                 |
|--------------------|---------------|--------------|--------------------|------|----------------|----------------------------|------------------|----------------------|--------------|--------------------------|-------------------------|
| 74CB3Q6800DBQRE4   | ACTIVE        | SSOP         | DBQ                | 24   | 2500           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-2-260C-1 YEAR  | -40 to 85    | CB3Q6800                 | <a href="#">Samples</a> |
| 74CB3Q6800DBQRG4   | ACTIVE        | SSOP         | DBQ                | 24   | 2500           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-2-260C-1 YEAR  | -40 to 85    | CB3Q6800                 | <a href="#">Samples</a> |
| 74CB3Q6800DGVRE4   | ACTIVE        | TVSOP        | DGV                | 24   | 2000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM   | -40 to 85    | BY800                    | <a href="#">Samples</a> |
| 74CB3Q6800DGVRG4   | ACTIVE        | TVSOP        | DGV                | 24   | 2000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM   | -40 to 85    | BY800                    | <a href="#">Samples</a> |
| SN74CB3Q6800DBQR   | ACTIVE        | SSOP         | DBQ                | 24   | 2500           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-2-260C-1 YEAR  | -40 to 85    | CB3Q6800                 | <a href="#">Samples</a> |
| SN74CB3Q6800DGV R  | ACTIVE        | TVSOP        | DGV                | 24   | 2000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM   | -40 to 85    | BY800                    | <a href="#">Samples</a> |
| SN74CB3Q6800PW     | ACTIVE        | TSSOP        | PW                 | 24   | 60             | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM   | -40 to 85    | BY800                    | <a href="#">Samples</a> |
| SN74CB3Q6800PWE4   | ACTIVE        | TSSOP        | PW                 | 24   | 60             | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM   | -40 to 85    | BY800                    | <a href="#">Samples</a> |
| SN74CB3Q6800PWG4   | ACTIVE        | TSSOP        | PW                 | 24   | 60             | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM   | -40 to 85    | BY800                    | <a href="#">Samples</a> |
| SN74CB3Q6800PWR    | ACTIVE        | TSSOP        | PW                 | 24   | 2000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM   | -40 to 85    | BY800                    | <a href="#">Samples</a> |
| SN74CB3Q6800PWRE4  | ACTIVE        | TSSOP        | PW                 | 24   | 2000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM   | -40 to 85    | BY800                    | <a href="#">Samples</a> |
| SN74CB3Q6800PW RG4 | ACTIVE        | TSSOP        | PW                 | 24   | 2000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM   | -40 to 85    | BY800                    | <a href="#">Samples</a> |

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.



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**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

| Device           | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74CB3Q6800DBQR | SSOP         | DBQ             | 24   | 2500 | 330.0              | 16.4               | 6.5     | 9.0     | 2.1     | 8.0     | 16.0   | Q1            |
| SN74CB3Q6800DGVR | TVSOP        | DGV             | 24   | 2000 | 330.0              | 12.4               | 6.9     | 5.6     | 1.6     | 8.0     | 12.0   | Q1            |
| SN74CB3Q6800PWR  | TSSOP        | PW              | 24   | 2000 | 330.0              | 16.4               | 6.95    | 8.3     | 1.6     | 8.0     | 16.0   | Q1            |

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

| Device           | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74CB3Q6800DBQR | SSOP         | DBQ             | 24   | 2500 | 367.0       | 367.0      | 38.0        |
| SN74CB3Q6800DGVR | TVSOP        | DGV             | 24   | 2000 | 367.0       | 367.0      | 35.0        |
| SN74CB3Q6800PWR  | TSSOP        | PW              | 24   | 2000 | 367.0       | 367.0      | 38.0        |

## DGV (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

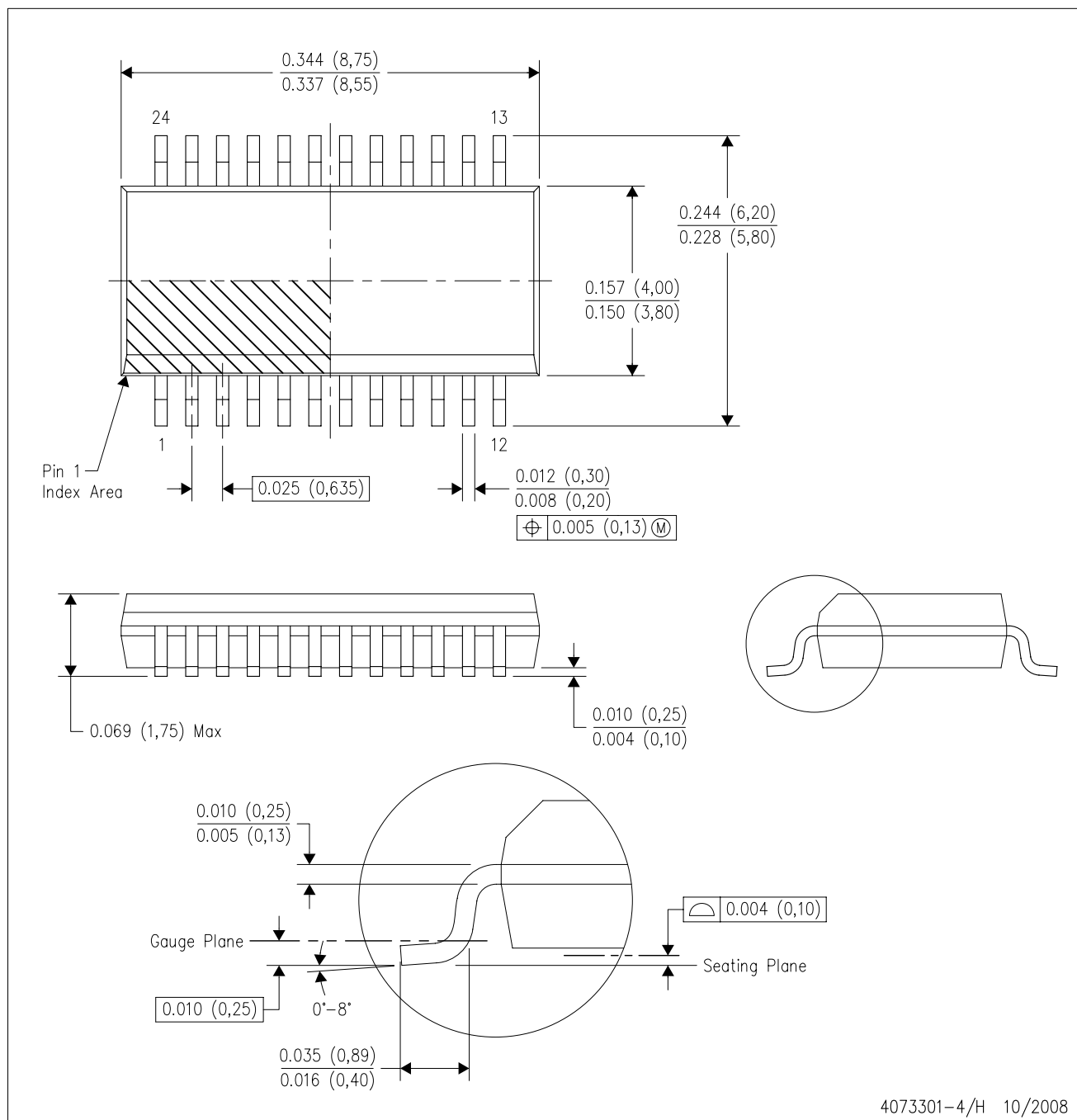
24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194

DBQ (R-PDSO-G24)

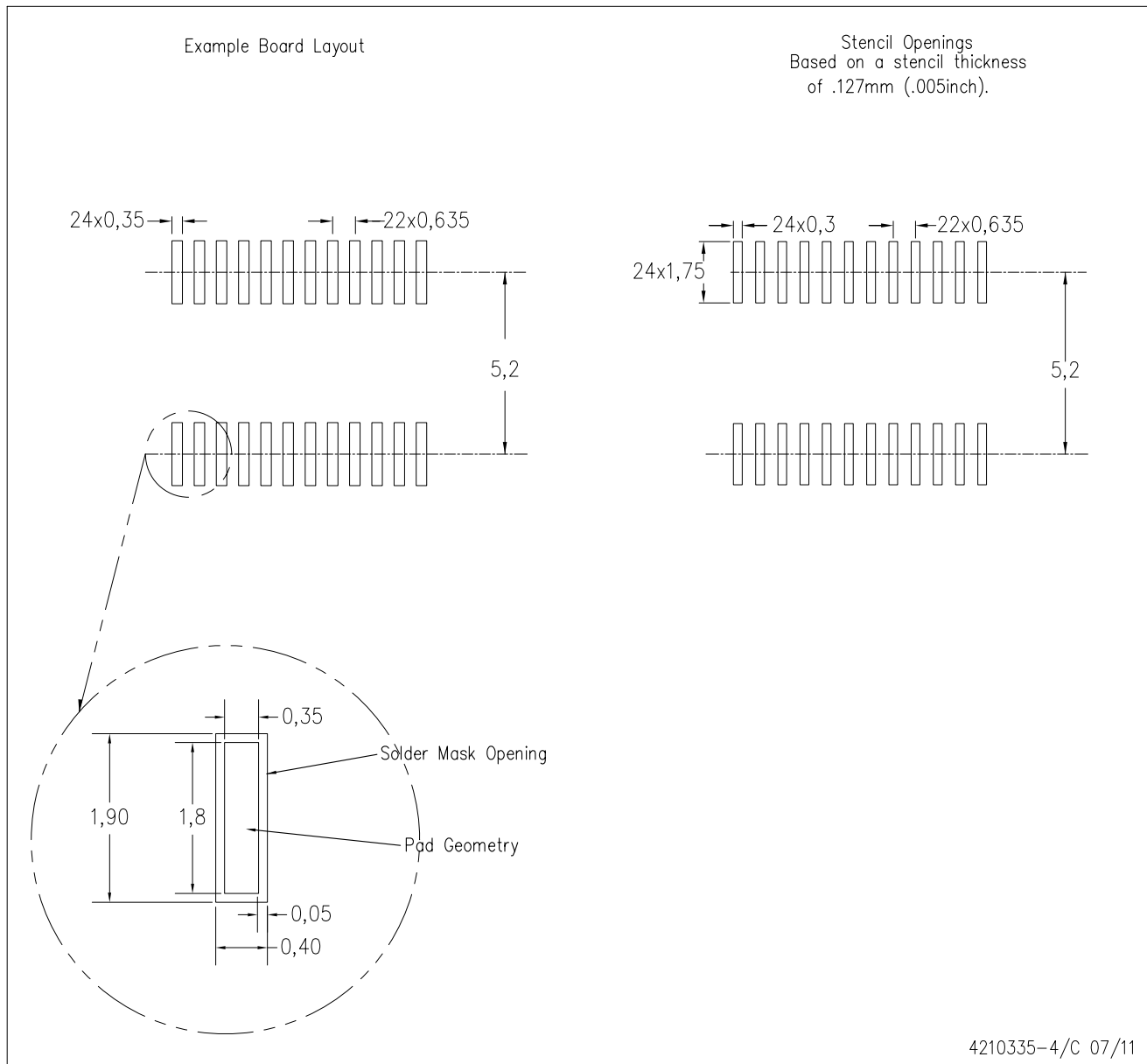
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
  - D. Falls within JEDEC MO-137 variation AE.

DBQ (R-PDSO-G24)

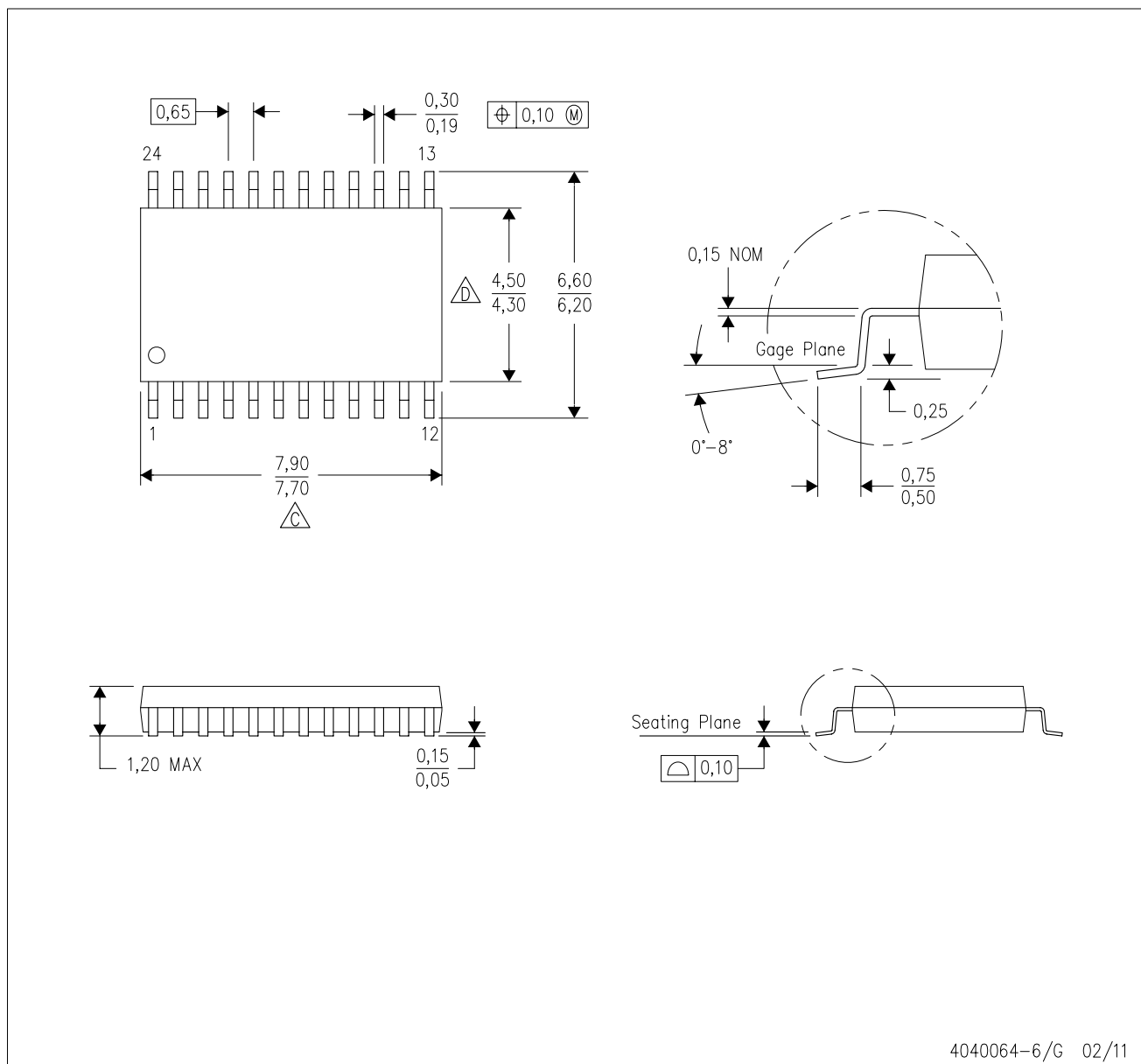
PLASTIC SMALL OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
  - D. Publication IPC-7351 is recommended for alternate designs.
  - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

PW (R-PDSO-G24)

PLASTIC SMALL OUTLINE

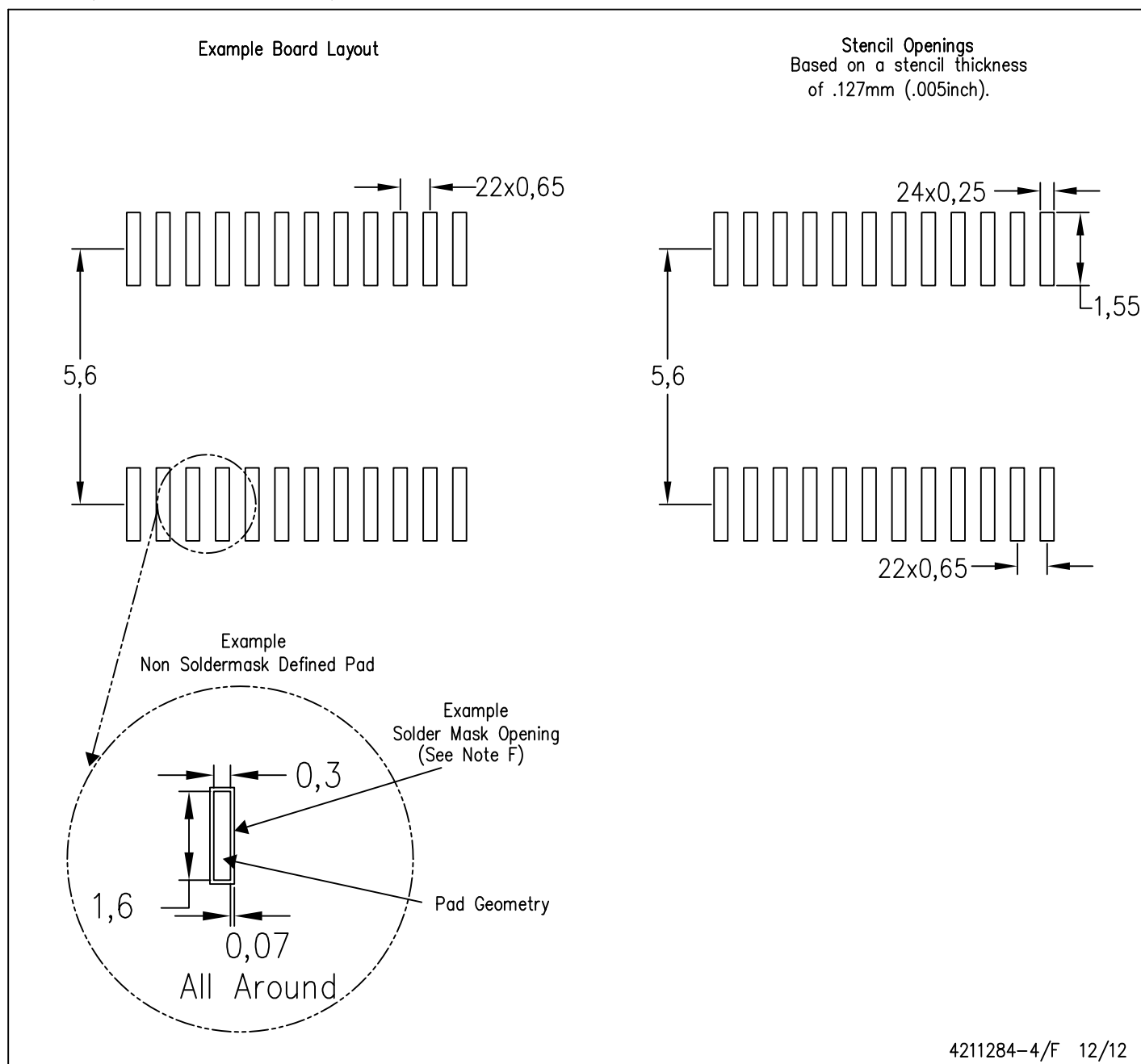


4040064-6/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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|                               |                                                                                          |
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